

Semiconductor devices - Mechanical and climatic test methods - Part 4: Damp heat, steady state, highly accelerated stress test (HAST)

EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

| | |
|---|--|
| See Eesti standard EVS-EN 60749-4:2017 sisaldab Euroopa standardi EN 60749-4:2017 ingliskeelset teksti. | This Estonian standard EVS-EN 60749-4:2017 consists of the English text of the European standard EN 60749-4:2017. |
| Standard on jõustunud sellekohase teate avaldamisega EVS Teatajas | This standard has been endorsed with a notification published in the official bulletin of the Estonian Centre for Standardisation. |
| Euroopa standardimisorganisatsioonid on teinud Euroopa standardi rahvuslikele liikmetele kättesaadavaks 16.06.2017. | Date of Availability of the European standard is 16.06.2017. |
| Standard on kättesaadav Eesti Standardikeskusest. | The standard is available from the Estonian Centre for Standardisation. |

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English Version

Semiconductor devices - Mechanical and climatic test methods -
Part 4: Damp heat, steady state, highly accelerated stress test
(HAST)
(IEC 60749-4:2017)

Dispositifs à semiconducteurs - Méthodes d'essais
mécaniques et climatiques - Partie 4: Essai continu
fortement accéléré de contrainte de chaleur humide (HAST)
(IEC 60749-4:2017)

Halbleiterbauelemente - Mechanische und klimatische
Prüfverfahren - Teil 4: Feuchte Wärme, konstant, Prüfung
mit hochbeschleunigter Wirkung (HAST)
(IEC 60749-4:2017)

This European Standard was approved by CENELEC on 2017-04-07. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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European foreword

The text of document 47/2346/FDIS, future edition 2 of IEC 60749-4, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60749-4:2017.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2018-01-07
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2020-04-07

This document supersedes EN 60749-4:2002.

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Endorsement notice

The text of the International Standard IEC 60749-4:2017 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

| <u>Publication</u> | <u>Year</u> | <u>Title</u> | <u>EN/HD</u> | <u>Year</u> |
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| IEC 60749-5 | - | Semiconductor devices - Mechanical and climatic test methods - Part 5: Steady-state temperature humidity bias life test | EN 60749-5 | - ¹⁾ |

1) To be published.

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